



IF 14, IF 09, IF 06 SOLDERWIRE ALLOYS

These alloys correspond to following specifications :

* International	: ISO 9453	* French	: NF EN 29453 - C 90550
* German	: DIN EN 29453 - DIN 1707	* English	: BS EN 29453 - BS 219

ALLOY Sn60 OR Sn60Pb40

General characteristics

Binary solder alloy used in many applications : electricity, electrical apparatus, electronics, ... The alloy approaches the eutecticum with a low melting point resulting in an easy use.

Physical and chemical data

Tin content, Sn	: 59.5 to 60.5 %	Specific gravity (20°C)	: 8.5
Lead content, Pb	: remainder	Mechanical resistance	: Hardness Brinell : 13 V
Melting point	: 183°C to 188°C	Tensile strength	: 33 N/mm ²
Max. impurity level	: 0.05 %	Electrical conductivity	: 11.5%/Cu

Packaging

This alloy can be presented as follows :

- * Wires * Available diameter : 0.35 mm (100 gr spool), 0.5 mm, 0.7 mm, 1 mm and 1.5 mm
- * Conditions : DIN spools of 500 gr.

The standard packaging is a cardboard box of 6 kg.

- * Flux incorporated : IF 14 Flux content : 1.4 %

ALLOY Sn63 OR Sn63Pb37

General characteristics

Binary solder alloy used in many applications : electricity, electrical apparatus, electronics and especially for the soldering of PCB's on automatic machines.

Physical and chemical data

Tin content, Sn	: 62.5 to 63.5 %	Specific gravity (20°C)	: 8.4
Lead content, Pb	: remainder	Mechanical resistance	: Hardness Brinell : 14 V
Melting point	: 183°C	Tensile strength	: 40 N/mm ²
Max. impurity level	: 0.05 %	Electrical conductivity	: 12 %/Cu

Packaging

This alloy can be presented as follows :

- * Wires * Available diameter : 0.35 mm (100 gr spools), 0.5 mm, 0.7 mm and 1 mm
- * Conditions : DIN spools of 500 gr.

The standard packaging is a cardboard box of 6 kg.

- * Flux incorporated : IF 14 Flux content : 1.4 %
IF 14-09 Flux content : 0.9 %
IF 14-06 Flux content : 0.6 %

ALLOY Sn62Pb36Ag2

General characteristics

This ternary soldering alloy is used in the electronic industry and especially in the presence of silver and golden surfaces.



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Advantages : * Mechanical resistance superior to S-Sn60Pb40E
* Better fluidity
* Alloy specially convenient on silver-plated surfaces

Physical and chemical data

Tin content, Sn	: 61.5 to 62.5 %	Specific gravity (20°C)	: 8.5
Lead content, Pb	: remainder	Mechanical resistance	: Hardness Brinell : 10 V
Silver content, Ag	: 1.8 to 2.2%	Tensile strength	: 45 N/mm ²
Melting point	: 178°C to 188°C	Electrical conductivity	: 15%/Cu
Max. impurity level	: 0.05 %		

Packaging

This alloy can be presented as follows :

- * Wires * Available diameter: 0.35 mm (100 gr spools), 0.5 mm, 0.7 mm and 1 mm
- * Conditions : DIN spools of 500 gr.

The standard packaging is a cardboard box of 6 kg.

- * Flux incorporated : IF 14 Flux content : 1.4 %
IF 14-09 Flux content : 0.9 %
IF 14-06 Flux content : 0.6 %

ALLOY Sn5Pb93Ag2

General characteristics

This ternary soldering alloy is used in the electronic industry and especially for high temperature tinning and stripping copper wires.

Advantages : * Higher melting point alloy
* Can be used up to 500°C
* Better electrical conductivity than other classic high temperature alloys (S-Pb92Sn8 ; S-Pb90Sn10)

Physical and chemical data

Tin content, Sn	: 4.8 to 5.2 %	Max. impurity level	: 0.05 %
Lead content, Pb	: remainder	Specific gravity (20°C)	: 11.10
Silver content, Ag	: 1.2 to 1.8 %	Mechanical resistance	: Hardness Brinell : 10 V
Melting point	: 296°C to 310°C		

Packaging

This alloy can be presented as follows :

- * Wires * Available diameter: 0.5 mm, 0.7 mm and 1 mm
- * Conditions : DIN spools of 500 gr.

The standard packaging is a cardboard box of 6 kg.

- * Flux incorporated : IF 14 Flux content : 1.4 %
IF 14-09 Flux content : 0.9 %
IF 14-06 Flux content : 0.6 %

ALLOY Sn96 OR Sn96Ag4

General characteristics

Binary solder without lead, used in the electronic industry but also in the medical and food industry.

Advantages : * Eutectic alloy with a melting point of 40°C higher than S-Sn63Pb37E
* Very good mechanical resistance.
* Shiny solder alloy, no dullness will occur.



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- * The electrical conductivity is very good.
- * Very nice solderjoints are made on stainless steel.
- * No presence of lead.

Physical and chemical data

Tin content, Sn	: remainder	Specific gravity (20°C)	: 10.4
Silver content, Ag	: 3.5 % to 4 %	Mechanical resistance	: Hardness Brinell : 14.8 V
Melting point	: eutecticum at 221°C	Electrical conductivity	: 14 % IACS

Packaging

This alloy can be presented as follows :

- * Wires * Available diameter : 0.35 mm (100 gr spools), 0.5 mm, 0.7 mm and 1 mm.
- * Conditions : DIN spools of 500 gr.

The standard packaging is a cardboard box of 6 kg.

- * Flux incorporated : IF 14 Flux content : 1.4 %
IF 14-09 Flux content : 0.9 %
IF 14-06 Flux content : 0.6 %

ALLOY Sn99Cu1

General characteristics

Binary solder without lead, used in the electronic industry and related industries.

Advantages : * Eutectic alloy containing 0.7% copper, with a melting point of 227°C.

- * Very good mechanical resistance.
- * Shiny solder alloy, no dullness will occur.
- * The electrical conductivity is very good.
- * No presence of lead.

Physical and chemical data

Tin content, Sn	: remainder	Specific gravity (20°C)	: 7.3
Copper content, Cu	: 0.45 % to 0.9 %	Mechanical resistance	: Hardness Brinell : 14 V
Melting point	: 227°C (0.7% Cu)	Electrical conductivity	: 14% IACS

Packaging

This alloy can be presented as follows :

- * Wires * Available diameter : 0.35 mm (100 gr spools), 0.5 mm, 0.7 mm, 1 mm and 1.5 mm
- * Conditions : DIN spools of 500 gr.

The standard packaging is a cardboard box of 6 kg.

- * Flux incorporated : IF 14 Flux content : 1.4 %
IF 14-09 Flux content : 0.9 %

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